

Micro-optics Functional Testing

Sébastien Reithinger Technical Leader Opto



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EPIC Technology Meeting on Photonics for Miniaturized Optics: From Components to Use-cases at Sony DADC





Alfamation: 33 years of expertise

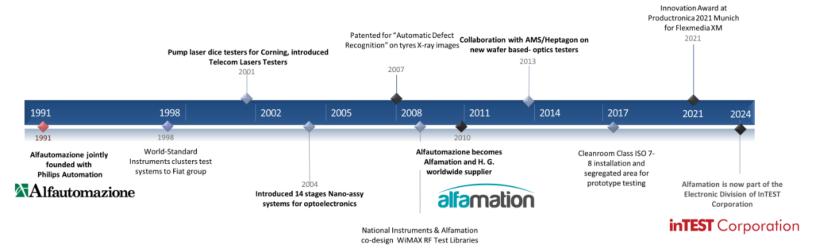


Headquarters in Lissone (MB) Italy Part of inTEST Corp. (NJ USA)

NYSE: INTT



Diversified Global Manufacturer of Innovative **Functional Test** Systems



Since 1991, a history of innovation

California
(entest tota)

California
(entest tota)

New York
(entest)

New York
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New Jork
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130+ Employees
2000+ Worldwide Installations
Global Presence through inTEST

- Strong R&D and Engineering
- Expertise in Optics
- Deep knowledge in Image Processing
- Experience in Optoelectronics and Photonics





- RF & Wireless
- Infotainment & Telematics
- 5G and V2X



- Consumer Electronics
- Displays
- PCBA Functional Test



- Audio Amplifier Test
- 32 Simultaneous Audio Channel **Testing**



flexmedia XM

MULTIPLE INSTRUMENTS, ONE FAMILY

- · Specialty Test Modules
- Audio-Video Generators/Analyzers
- Camera Simulators
- Ethernet-powered, OS-Agnostic

Hyperion™ Common Test Platform



William 55 mm alfamation

PIXELSHOOTER™

Fully Automated Display & Instrument Cluster Tester



WALOT WAfer-Level-Optics Tester

High-volume micro-optics manufacturing test

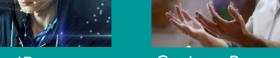


Micro-optics Functional Testing "What does it mean on the production floor?"



Consumer Electronics 3D Sensing





Face ID

Gesture Recognition

DOE (Diffractive Optical Element) Collimator lens VCSEL Array Tested at wafer-level

Performance

Test Metrics: Angular position, Efficiency, Uniformity. Up to **3000 UPH** (Units per hour)

Gage R&R < 10%

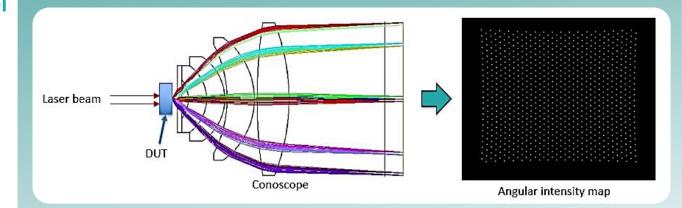
50 Mpx, 105° or 150° field of views

< 0.5° optical resolution

Conoscopy

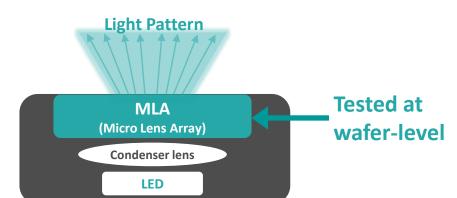












Performance

Test Metrics: Dimensions, Sharpness, Brightness, Ghosts.

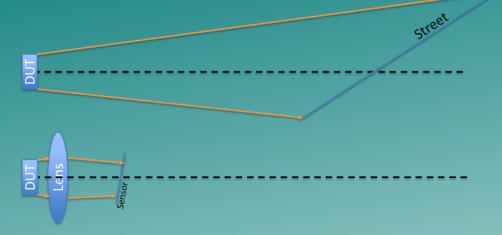
Automated setup flexibility

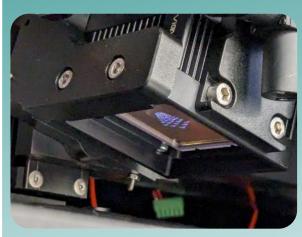
Up to **2500 UPH**

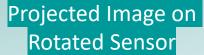
Gage R&R < 10%

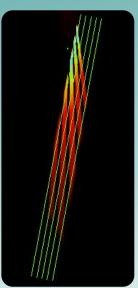
Sub-mm resolution on target image surface

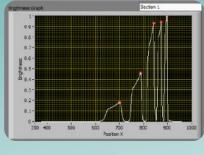
Light Pattern Projector Testing





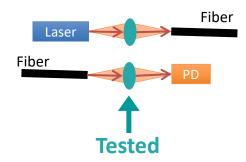












Performance

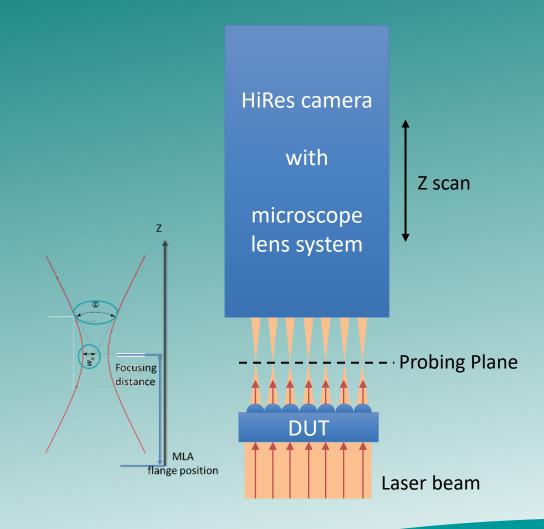
Metrics: Uniformity, Flange Focal Length, Efficiency,...

Up to **1500 UPH**

Gage R&R < 10%

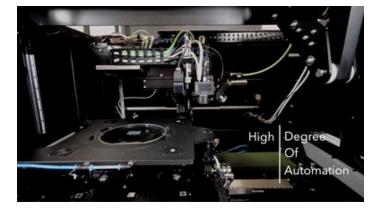
Z Scan resolution < 5 um

Coupling Optics Testing





What makes a good ATE? (Automated Test Equipment)



High Throughput



- Optimized test sequence
 - Parallel processes
 - Batch sequencing
- Built-in step-by-step test time analyzer

Test Reliability



- Automated calibration sequences
- Golden units monitoring
- Built-in statistical tools

Cost optimization



- Sweet spot among:
 - Instruments perf
 - Testing scope
 - Testing time
 - Test flexibility
- Standard base platform
 - Common base components and spare parts

Cleanroom Friendly

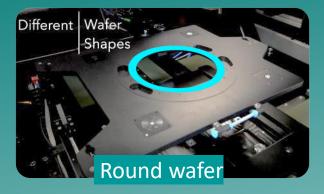


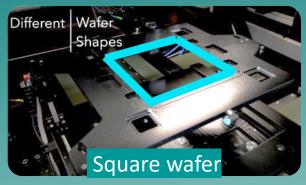
- Automated serial number reading and alignment
- Robotized wafer loading
- Reduced footprint
- Cleanroom compatible
- Network integration



No Standard → **Flexibility**

- Various Wafers sizes, shapes and thickness
- Wafer fixing :
 - Vacuum
 - Clamping
- Beam shaping of LED or Laser, with controlled:
 - Polarisation
 - Divergence
 - Intensity profile
 - Active area size and shape.





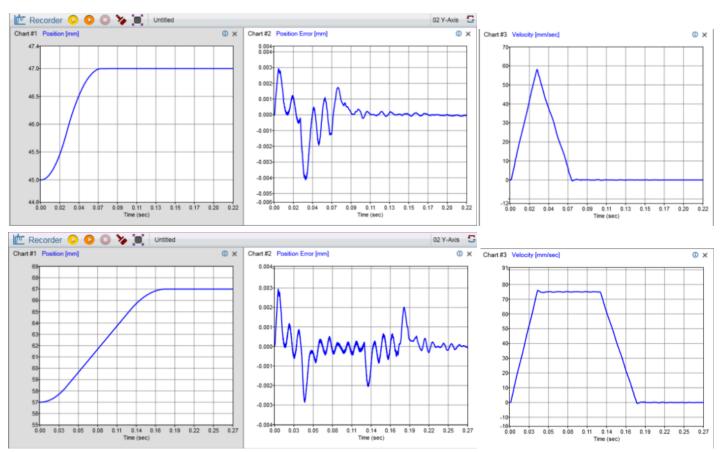




Stepping from DUT to DUT in less than 200ms

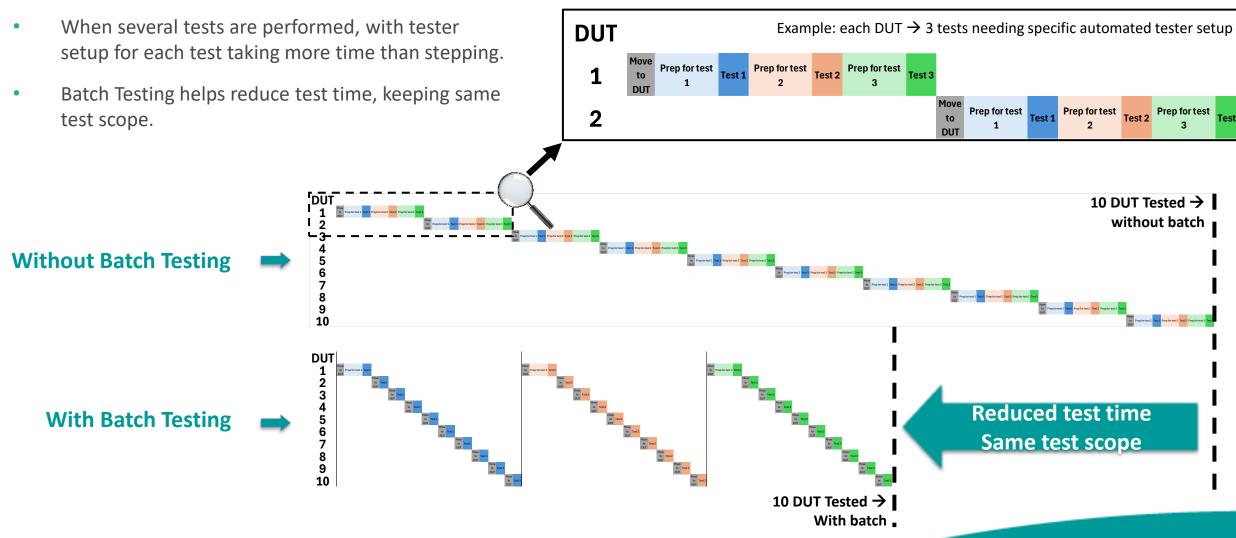
Step size	Stepping time (Settling within 300nm)
2 mm	90 ms

Step size	Stepping time (Settling within 300nm)
10 mm	200 ms





Time optimization strategy for complex test scopes



Being EPIC together

- What can You do for Alfamation?
 - test method
 - instrument
 - micro-optics and photonics test challenge
- What can Alfamation do for You?
 - Supply Automated Test Equipment
 - Develop new test methods
 - Not only at wafer-level!





